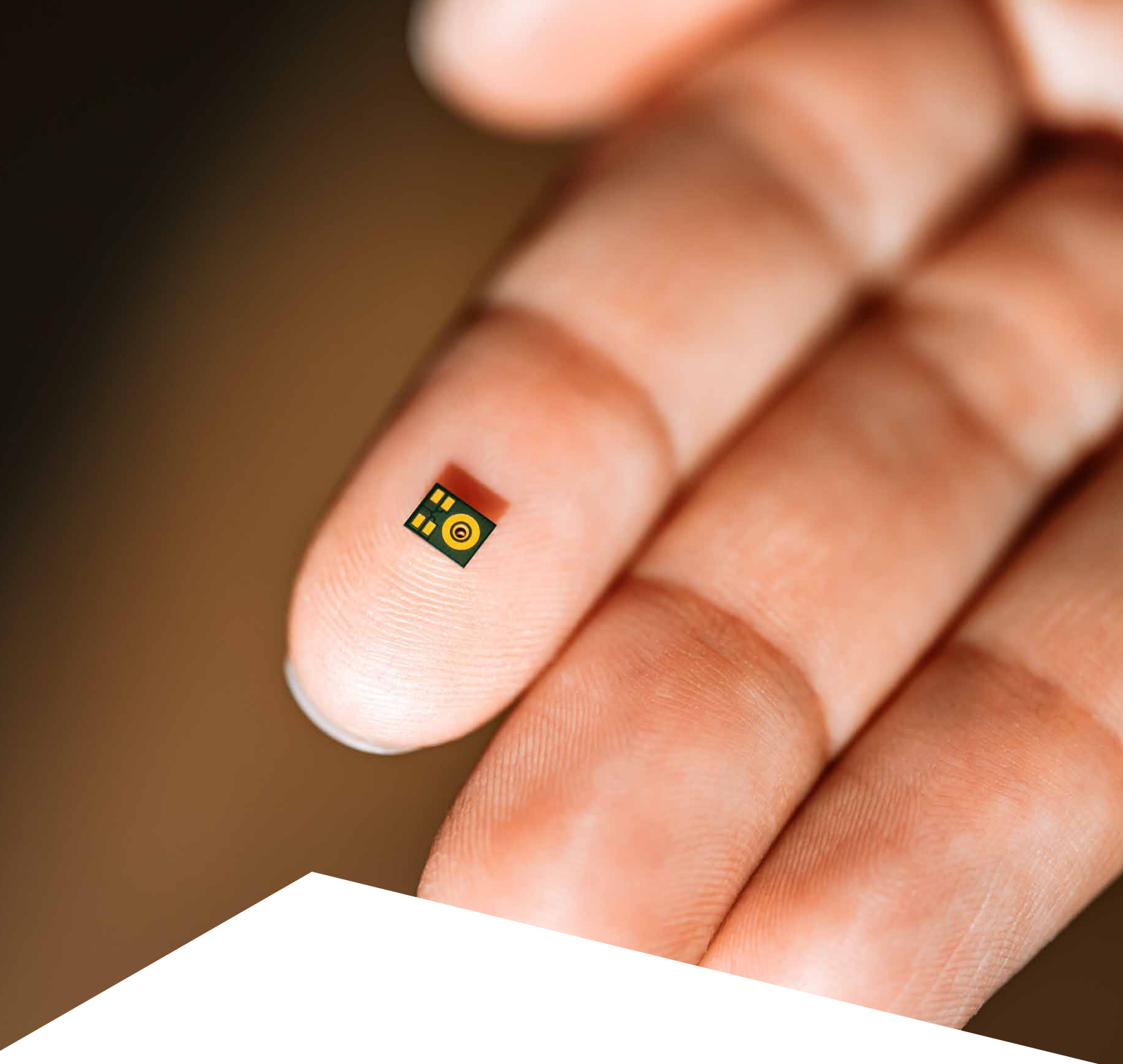




XENSIV™ MEMS microphones

For automotive, industrial and consumer applications

www.infineon.com/mems-microphones





XENSIV™ MEMS microphones

**For automotive, industrial, and consumer applications
– redefine a growing number of use cases**

XENSIV™ MEMS microphones are setting new performance benchmarks across a growing number of industries. These innovative silicon microphones are designed to provide the benefits of the lowest possible self-noise (high SNR) and minimal distortion for an ever-expanding range of applications.

Dedicated digital and analog MEMS microphones

Our digital and analog MEMS microphones for consumer applications deliver a studio-quality audio experience in compact form factors such as smartphones or earbuds. On the other hand, our automotive-qualified solutions enable the best audio performance in harsh automotive environments, improving the in-cabin user experience and passenger comfort. Additionally, they enhance autonomous driving features and contribute to road safety.

MEMS microphones for consumer and industrial applications

Infineon's XENSIV™ MEMS microphones are designed to capture unprecedented precision and quality audio signals. The microphones comprise Infineon's MEMS microphone chips and ASICs, the world's best-selling microphone components.

Due to advanced technical characteristics, high-quality standards, and robustness at the chip level, XENSIV™ MEMS microphones add 'hearing' to many consumer applications (earbuds, headphones, wearables, smart speakers, laptops, tablets, etc.) and industrial and medical applications (predictive and preventive maintenance, security, patient monitoring systems, etc.).

MEMS microphones for automotive applications

We also offer high-performance MEMS microphones qualified to the AEC-Q103-003 automotive quality standard. They are suited for all applications inside and outside the car where the best audio performance in harsh automotive environments is required. The extended availability of these silicon devices matches the typical long lifecycle of a vehicle.

Typical applications include speech (hands-free/e-call/ICC), voice commands with microphone arrays and beam-forming, active and road noise cancellation, and detecting event sounds, sirens, contact, and road conditions.

The extended availability of these silicon devices matches a vehicle's typical long lifecycle, revolutionizing the use of automotive microphones for a wide range of applications.



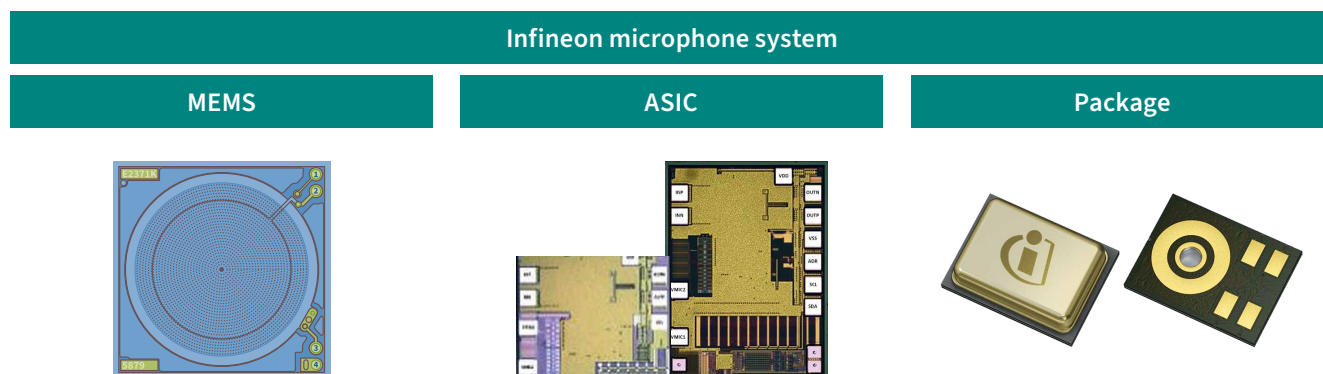
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MEMS microphones technology

Infineon's XENSIV™ MEMS microphones are designed to capture audio signals with unprecedented precision and quality. The microphones consist of Infineon's

MEMS microphone chips and ASICs, which are widely regarded as the world's best-selling microphone components.



Infineon owns all building blocks of MEMS microphones allowing to develop MEMS, ASIC, and package combina-

tions which achieve the best possible performance and are optimized to each application.

Infineon XENSIV™ MEMS microphones shape the industry on the technology level

MEMS microphones use an electrically charged backplate and a membrane to form a capacitive sound transducer. The flexible membrane moves proportionally to the amplitude and frequency of incoming sound waves.

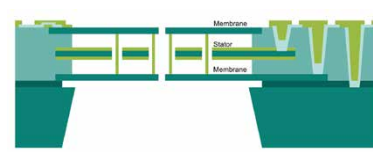
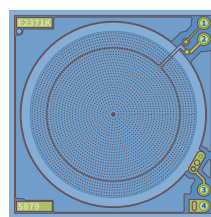
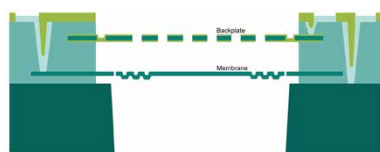
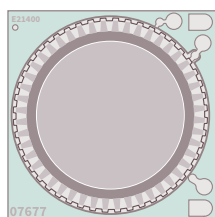
Single backplate technology (SBP)

Single backplate technology (SBP) represents an industry standard for mid-end microphones with its simplicity and robustness. The SBP technology offers the best performance-to-cost ratio, especially for small package sizes and SNR values up to 69 dB SNR.

The resulting change in voltage is measured, processed and output by an integrated analog or digital ASIC. Infineon distinguishes two main MEMS technologies:

Sealed dual membrane (SDM)

Sealed dual membrane (SDM) is Infineon's revolutionary MEMS microphone technology that utilizes two membranes and a charged stator to create a sealed low-pressure cavity and a differential output signal. The architecture enables ultrahigh SNR (up to 75 dB SNR) and very low distortions and delivers high ingress protection (IP57) at a microphone level. Select SDM technology for best-in-class acoustic performance in medium and larger packages.



Click here to learn more:

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MEMS microphones for automotive applications

Qualified according to automotive standard, AEC-Q103-003

As part of our comprehensive XENSIV™ microphone family, we also offer automotive microphones, especially tested and qualified to the stringent needs of automotive use cases. These microphones close the gap in the automotive industry, providing the best possible fit for automotive applications.

XENSIV™ MEMS microphones for automotive – product portfolio

	Product	Classification	Key features	Inter- faces	Package di- mensions [mm ³]	SNR [dB(A)]	AOP [dB]	Sensitivity [dBFS]	Current consump- tion [μA]	Environ- mental robust- ness	Operating temp. [°C]
Digital	IM63D135A	AEC-Q103-003	Optimized for ex- ternal applications	PDM	3.50 x 2.65 x 0.98	63.5	135	-41	1100	IP57	-40 to +105
	IM64D121A	AEC-Q103-003	Optimized for mid performance use cases	PDM	3.50 x 2.65 x 0.98	64	121	-26	1100	IP57	-40 to +85
	IM64D130A	AEC-Q103-003	Optimized for mid performance use cases	PDM	3.50 x 2.65 x 0.98	64	130	-36	1100	IP57	-40 to +85
	IM66D120A	AEC-Q103-003	Optimized for ANC and speech	PDM	3.50 x 2.65 x 0.98	66	120	-26	1100	IP57	-40 to +105
	IM66D130A	AEC-Q103-003	Optimized for ANC and speech	PDM	3.50 x 2.65 x 0.98	66	130	-36	1100	IP57	-40 to +105
	IM67D120A	AEC-Q103-003	Optimized for speech	PDM	4.00 x 3.00 x 1.20	67	120	-26	980		-40 to +105
	IM67D130A	AEC-Q103-003	Optimized for speech	PDM	4.00 x 3.00 x 1.20	67	130	-36	980		-40 to +105
Analog	IM64A130A	AEC-Q103-003	Optimized for mid performance use cases	Analog single- ended	3.35 x 2.50 x 0.98	64	130	-38	105	IP57	-40 to +85
	IM68A130A	AEC-Q103-003	Optimized for ANC	Analog single- ended	3.35 x 2.50 x 0.98	68	130	-38	105	IP57	-40 to +105

Key features and benefits of automotive qualified microphones

- Full automotive qualification according to AEC-Q103-003
- Increased operating temperature range up to +105°C ¹⁾
- Environmental robust up to IP57 ¹⁾
- Narrow sensitivity matching for enhanced performance of beam-forming arrays
- Flat frequency and stable phase response down to 7 Hz for optimal performance in acoustic noise cancellation (ANC) applications ¹⁾
- Very high AOP for high wind-noise robustness ensures stable performance in extremely loud environments of exterior use cases ¹⁾
- Best-in-class audio performance (SNR, AOP, THD) for optimum speech quality and capture of distortion-free audio signals in loud environments such as inside a car



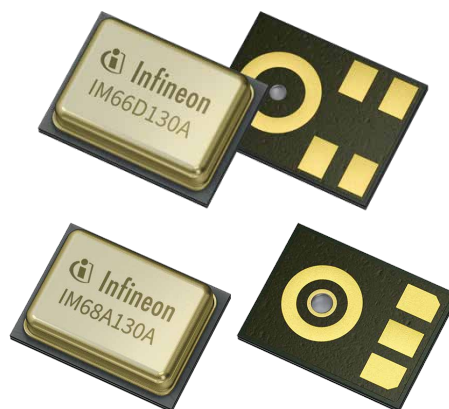
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¹⁾ Depending on selected product. See parameter table above for details.

Customer benefits of automotive qualified microphones

Cost saving	– Reduced re-qualification cost for Tier 1 due to minimized risk of qualification failure – Longer available parts enable platform concepts at Tier1/OEM
Quality	– Quality assured for the whole vehicle life by running qualification tests at three different temperatures over the full operating temperature range (-40°C to +105°C) – Compliance with AEC-Q103 and automotive style documentation (PPAP, Qual report, ...) simplifies OEM discussions (no waivers needed)
Performance	– Characterization data over full temperature range provides full transparency of acoustic behavior and avoids late discrepancies – Best-in-class audio performance leads to increased speech intelligibility and improved satisfaction of the end user
Flexibility	– Extended temperature range allow flexible use in different operational areas (internal and external) and various applications – High acoustic-overload-point (AOP) allows flexible placement inside/outside the vehicle
Service and knowledge	– Good reputation of Infineon-Automotive simplifies product selection procedures with OEMs – Premium services with our worldwide support teams shorten the learning curve and design-in cycles – Fast FAR handling, including high traceability, facilitates efficient incident management



Click here to learn more:

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Typical applications for automotive MEMS microphones in-cabin and outside of the vehicle



Speech: Hands free/e-call/ICC

Enabling distortion-free audio capturing for all speech-related applications thanks to the high SNR and low distortions.

Recommended products:

IM64A130A, IM64D121A, IM64D130A, IM66D120A, IM66D130A, IM68A130A

Interior



Speech: Microphone arrays/beamforming

Improved beam forming and noise suppression capabilities of microphone arrays, due to the narrow sensitivity and phase matching.

Recommended products:

IM66D120A, IM66D130A, IM67D120A, IM67D130A

Interior



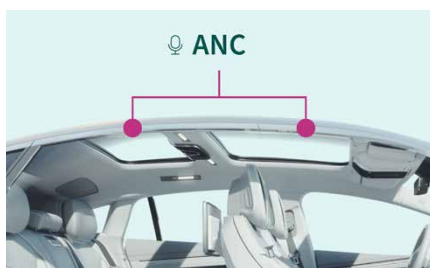
Speech recognition/voice commands

Best speech intelligibility for speech recognition due to high SNR and low distortions.

Recommended products:

IM66D120A, IM66D130A, IM67D120A, IM67D130A, IM68A130A

Interior



Active and road noise cancellation (ANC/RNC)

Enabling a quiet environment for comfortable travels with best ANC performance, thanks to the flat and stable frequency and phase response at lowest frequencies.

Recommended products:

IM66D120A, IM66D130A, IM68A130A

Interior



Event sound detection/siren detection

The large dynamic range and high acoustic overload point contribute to road safety by detecting sounds like sirens from emergency vehicles or even dangerous road conditions.

Recommended products:

IM63D135A, IM66D130A, IM68A130A

Exterior



Voice recognition/external interaction

Allowing external interaction via voice commands and good speech intelligibility due to high SNR and low distortions (THD)

Recommended products:

IM66D130A, IM63D135A

Exterior



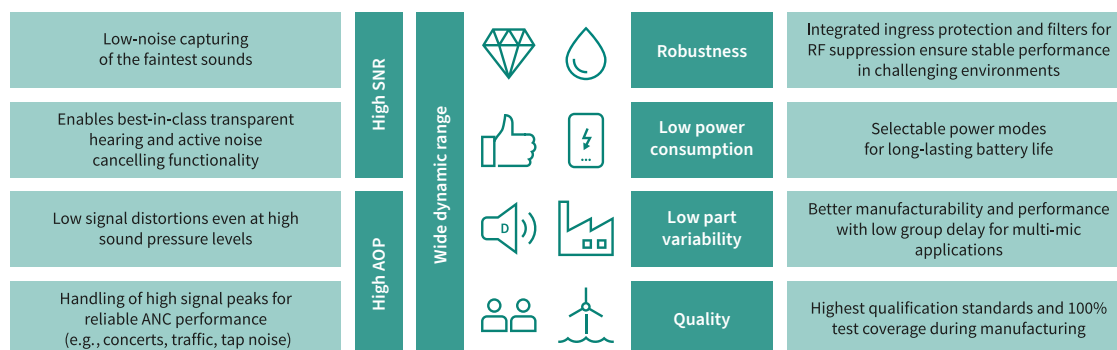
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MEMS microphones for consumer applications

XENSIV™ MEMS microphones feature ultralow self-noise (high SNR), extremely low distortions (THD) even at high sound pressure levels (SPL), very tight part-to-part phase and sensitivity matching, a flat frequency response with a low LFRO (low frequency roll-off), and an ultralow group delay.

With selectable power modes and a very small package size, Infineon XENSIV™ MEMS microphones are an excellent match for consumer electronics, offering outstanding audio-capturing capabilities, as well as for industrial applications, such as predictive maintenance and security.



XENSIV™ MEMS microphones for consumer - product portfolio

	Product	Key features	Interface	Package dimensions [mm ³]	SNR [dB(A)]	AOP (1/10%THD) [dB SPL]	Current consumption [μA]	Sensitivity [dBFS]	LFRO [Hz]
Digital	IM69D130	High SNR and high AOP	PDM	4.00 x 3.00 x 1.20	69	128/130	980 (at 3.072 MHz)	-36 dBFS	28
	IM69D120	High SNR and sensitivity	PDM	4.00 x 3.00 x 1.20	69	118/120	980 (at 3.072 MHz)	-26 dBFS	28
	IM69D127	High performance in small size	PDM	3.60 x 2.50 x 0.98	69	123/127	980 (at 3.072 MHz)	-34 dBFS	40
	IM69D128S	Ultralow current consumption	PDM	3.50 x 2.65 x 0.98	69	125/128	520 (at 3.072 MHz)	-37 dBFS	30
	IM67D128B	Ultralow power	PDM	3.00 x 2.00 x 0.98	67	128	540 (at 3.072 MHz)	-37 dBFS	10
	IM70D122	High SNR and sensitivity	PDM	3.50 x 2.65 x 0.98	70	120/122	980 (at 3.072 MHz)	-26 dBFS	30
	IM72D128	Ultrahigh SNR	PDM	4.00 x 3.00 x 1.20	72	126/128	980 (at 3.072 MHz)	-36 dBFS	20
	IM73D122	Ultrahigh SNR and sensitivity	PDM	4.00 x 3.00 x 1.20	73	120/122	980 (at 3.072 MHz)	-26 dBFS	20
	IM72D128V	Ultralow current consumption	PDM	4.00 x 3.00 x 1.20	71.5	125/128	430 (at 3.072 MHz)	-36 dBFS	11
	IM68D121J	High SNR, high sensitivity and low IDD	PDM	3.50 x 2.65 x 0.98	68	118/121	580 (at 3.072 MHz)	-26 dBFS	20
	IM68D128B	High SNR and low IDD	PDM	3.50 x 2.65 x 0.98	67.5	122/128	580 (at 3.072 MHz)	-37 dBFS	20
	IM66D132H	High 1%/10% THD and low IDD	PDM	3.50 x 2.65 x 0.98	66	128/132	580 (at 3.072 MHz)	-37 dBFS	20
	IM69D129F	Ultralow power	PDM	3.50 x 2.65 x 0.98	69	127/129	450 (at 3.072 MHz)	-36 dBFS	11
	IM66D130M	Small package and low IDD	PDM	3.00 x 2.00 x 0.98	66	124/130	550 (at 3.072 MHz)	-37 dBFS	35
Analog	IM68A130	Small package and low LFRO	Single-ended	3.35 x 2.50 x 0.98	68	118/130	110 (at 2.75 V)	-38 dBV	10
	IM70A135	High SNR and high AOP	Differential	3.5 x 2.65 x 0.98	70	132/135	170 (at 2.75 V)	-38 dBV	37
	IM73A135	Ultrahigh SNR and high AOP	Differential	4.00 x 3.00 x 1.20	73	132/135	170 (at 2.75 V)	-38 dBV	20

All XENSIV™ consumer microphones feature a bottom port. All sealed dual membrane (SMD) XENSIV™ microphones deliver IP57 ingress protection at the component level, ensuring better manufacturability and enhanced robustness against water and dust.



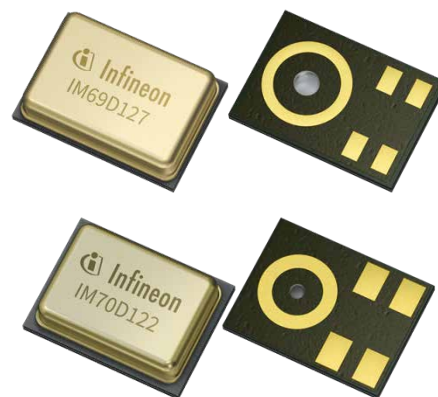
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Features, applications, and use cases for MEMS microphones for consumer

Features

- Ultralow self-noise/ultrahigh SNR
- Selectable power modes for longer battery life
- Sealed dual membrane (SDM) technology with ingress protection at the microphone level
- Extremely low distortion (THD), even at high sound pressure levels (SPL)
- High dynamic range and very high acoustic overload points (AOP)
- Very tight part-to-part phase and sensitivity matching
- Flat frequency response with a low LFRO (low-frequency roll-off)
- Ultralow group delay for multi-microphone applications
- Very small package sizes for various applications



Typical use cases

- Studio quality audio capturing for communication devices
- Low-latency wide-band audio signal capturing for active noise cancellation (ANC) and transparent hearing functionality
- Small form factor and current consumption for battery and size-constrained devices
- Multi-microphone (array) based beamforming and source separation for audio zoom features and multiuser audio capturing
- High range, far field voice pickup for multi room applications
- Capturing of audio signals in loud environments, such as outdoor
- Audio pattern detection for predictive and preventive maintenance and security

Applications

- TWS earbuds
- ANC headphones
- Smart speakers
- Conference speakers
- Laptops/tablets
- Wearables
- AR/VR devices
- Cameras
- Video doorbells
- Smart home
- Smart infrastructure
- Home appliances
- Industrial applications
- Medical applications

Visit the [Infineon Developer Community](https://www.infineon.com/developer-community) to get the support on your design with our audio experts. Furthermore, you can delve into Knowledge Based Articles, learn about MEMS mics specifications, foundational differences between ECM and MEMS technologies, get electrical implementation hints, and so much more!



Click here to learn more:

www.infineon.com/mems-microphones

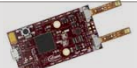
XENSIV™ MEMS microphone boards

The Infineon Audiohub Nano

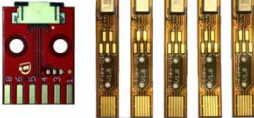
The Infineon Audiohub Nano enables better evaluation of Infineon XENSIV™ microphones. The kit includes an Infineon Audiohub Nano and four microphones on flex board. Up to two additional Infineon XENSIV™ MEMS microphones can be connected to the mono or stereo

output evaluation board. The evaluation board provides a USB audio interface to stream audio data from the microphone to any audio recording and editing software. The board has two different interfaces: analog and digital.

XENSIV™ MEMS microphones Audiohub Nano boards

Board	Description	SP	OPN	Audiohub Nano boards
EVAL_AHNB_DIGITALV01	Audiohub Nano Digital XENSIV™ MEMS microphones evaluation board	SP005955184	EVALAHNB DIGITALV01TOBO1	
EVAL_AHNB_ANALOGV01	Audiohub Nano Analog XENSIV™ MEMS microphones evaluation board	SP005568087	EVALAHNB ANALOGV01TOBO1	

XENSIV™ MEMS microphones flex boards

Board	Key features	SP	OPN	Flex kit
EVAL_IM69D120_FLEXKIT	- Quick and easy connection to evaluation system - Small size: 25 x 4.5 mm² - Pre-soldered MEMS microphone - Configurable select pin configuration for digital microphones	SP002153026	EVALIM69D120FLEXKITTOBO1	
EVAL_IM69D130_FLEXKIT		SP002153022	EVALIM69D130FLEXKITTOBO1	
KIT_IM66D130MV01_FLEX		SP006038060	KITIM66D130MV01_FLEXTOBO1	
KIT_IM66D132HV01_FLEX		SP006038061	KITIM66D132HV01_FLEX TOBO1	
KIT_IM68A130V01_FLEX		SP005728206	KITIM68A130V01FLEXTOBO1	
KIT_IM68D121JV01_FLEX		SP006155584	KITIM68D121JV01FLEXTOBO1	
KIT_IM68D128BV01_FLEX		SP006114517	KITIM68D128BV01_FLEX TOBO1	
KIT_IM69D127V11_FLEX		SP005403891	KITIM69D127V11FLEXTOBO1	
KIT_IM69D128SV01_FLEX		SP005744505	KITIM69D128SV01FLEXTOBO1	
KIT_IM69D129FV01_FLEX		SP006038667	KITIM69D129FV01FLEXTOBO1	
KIT_IM70A135V01_FLEX		SP005728204	KITIM70A135V01FLEXTOBO1	
KIT_IM70D122V01_FLEX		SP005826638	KITIM70D122V01FLEXTOBO1	
KIT_IM72D128V01_FLEX		SP005429924	KITIM72D128V01FLEXTOBO1	
KIT_IM72D128VV01_FLEX		SP006038668	KITIM72D128VV01FLEXTOBO1	
KIT_IM73A135V01_FLEX		SP005415695	KITIM73A135V01FLEXTOBO1	

XENSIV™ Audio Shield for MEMS microphones evaluation

The XENSIV™ Audio Shield simplifies the evaluation of up to 8 XENSIV™ MEMS microphones, facilitating the exploration of complex arrays and algorithms for applications in beamforming or AI. The shield is equipped with an Arduino interface, an audio codec, and a headset jack, and is compatible with the available PSOC™ 6 evaluation kits.

Board	SP	OPN	Audiohub Nano boards
EVAL_XENSIV_AUDIO_SHLD	SP006237639	EVALXENSIVAUDIOSHLDTOBO1	



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Shield2Go

Microcontroller



Product name: XMC1400 2Go kit

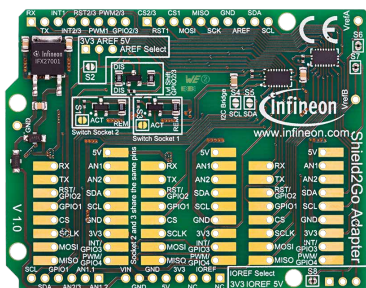
Sales name: KIT_XMC14_2GO

Ordering code: SP006065576

Product
information



MyIoT Adapter



Product name: MyIoT Adapter

Sales name: MY IOT ADAPTER

Ordering code: SP002434972

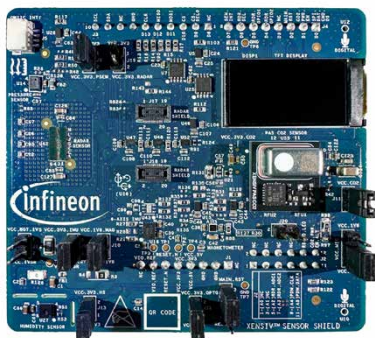
Infineon's Shield2Go boards offer a unique customer and evaluation experience – the boards are equipped with one Infineon IC and a ready-to-use Arduino library. Customers can now develop their own system solutions by combining Shield2Go boards with Infineon MyIoT adapters.

MyIoT adapters are gateways to external hardware solutions like Arduino and Raspberry Pi, popular IoT hardware platforms. This enables the fastest evaluation and development of IoT systems.

Product
information



XENSIV™ Sensor Shield



Product name: XENSIV™ Sensor Shield

Sales name: SHIELD_XENSIV_A

Ordering code: SP006018677

Infineon's XENSIV™ Sensor Shield provides seamless hardware compatibility between sensors, microcontrollers, and connectivity products. When paired with an MCU / Wi-Fi baseboard via the Arduino UNO interface, the board enables developers to quickly evaluate and develop with environmental sensors like:

- 60 GHz radars
- PDM microphones
- Pressure sensors
- Six-axis IMU
- Three-axis magnetometer
- Temperature and humidity

The shield also features a TFT display (80x160), and OPTIGA™ Trust-M secure element, and a QWIIC connector for additional peripheral expandability.

Product
information



Click here to learn more:

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www.infineon.com/pressure-sensors

www.infineon.com/current-sensors
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Dependability is the key driver for the megatrend towards autonomous driving

The future car will be fully connected and always online. It will be all-electric and autonomous. At Infineon, we believe that realizing this vision requires both technology and trust.

The growing demand for safe electronic systems in vehicles that drivers and passengers can rely on lays the foundation for trust and drives progress toward higher levels of automated driving.

Earning the trust of tomorrow's passengers begins with dependable electronics that enable highly available, reliable, robust, safe, and secure systems, capable of operating in all conditions.

Infineon is your trusted partner, offering all the essential components for your dependable systems – automotive quality, functional safety, cybersecurity, innovative products, system expertise, and operational excellence.

Dependable electronics for safer, smarter vehicles

As vehicles become increasingly reliant on electronic components, demand for safe, reliable systems continues to grow. Rising levels of automated driving especially depend on drivers' and passengers' trust in the quality and reliability of each component. The complexity and requirements in the automotive industry are expected to increase further, particularly in terms of quality and dependability, to ensure vehicles operate safely and smoothly throughout their 15-year lifespan.

Infineon's commitment to delivering high-quality, dependable products has resulted in a portfolio that offers superior performance and unmatched durability, driven by our zero-defect mentality. We go beyond industry standards to meet the real-world requirements of applications.

Enhance your automotive systems and applications with our high-quality semiconductor components designed for your needs.

Dependable electronics based on quality

Automotive quality beyond the standards with a zero-defect mindset.

Vehicle complexity and functionality will continue to grow, driving the need for dependable electronics, with quality being one of its key ingredients. Our passion for quality creates a product portfolio that meets high standards and delivers highly reliable, robust products.

How Infineon differentiates as a quality leader:

1. Our goal is to go beyond standards to better meet real application requirements: from intensive screening methods to detect production defects, to advanced AEC Q100/101 tests (where required), to sub-1 dpm validation aimed at achieving ultralow defect rates.
2. Our track record of achievements, including multiple quality awards from customers such as Toyota (Honor Quality Award in 2020) and Continental (Supplier of the Year in 2019), demonstrates that we consistently meet and exceed outstanding quality targets in the automotive industry.
3. Infineon offers best-in-class customer service, supported by a regional network of failure analysis labs, strong localized expertise, technical training programs, and state-of-the-art regional quality analysis labs equipped for advanced failure analysis.
4. We meet customer needs through industry-leading product requirements, design, manufacturing, and testing practices. Quality is integrated into our development processes (e.g., RDDF), design rules (e.g., ADeGo), materials, manufacturing processes, process controls, proprietary testing, and screening methods.

Infineon's Zero Defect mentality is built upon:

- Producing 24/7/365 at sub-dpm levels: Translated into a year's timeline, this means we deliver zero defects for all but the last three seconds of the year.
- Delivering sub-ppm quality levels.
- Achieving Zero Defect status for 90 percent of our products.

We go beyond the standards to better meet real application requirements.



Click here to learn more:

www.infineon.com/magnetic-position-sensors
www.infineon.com/pressure-sensors

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www.infineon.com/mems-microphones

www.infineon.com/gas-sensors
www.infineon.com/radar-sensors



Infineon support for sensors

Useful links and helpful information

Further information, datasheets, and documents

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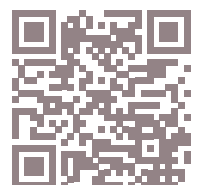
Boards
and designs



Tools



Play





Infineon powerful support

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Infineon customized solutions

Your specific needs, realized



A customized solution (commonly known in the industry as an ASIC — Application Specific IC, or CSP — Customer Specific Product) is designed, planned, developed, and used for a specific purpose. Its mission is to be optimized and efficient, with all the required functionalities and features for a specific application for a single customer.

Infineon as your one-stop-shop from design to delivery



Infineon, as a market leader in customized solutions, believes innovation comes through collaboration and exploring new paths. Working closely with our customers, understanding their needs, and combining their needs with our cutting-edge solutions, we know there is always a benefit for every customer and application. Whether the challenge is related to IP or BOM constraints or requires higher integration, an ASIC can be the solution. Furthermore, customers benefit from Infineon's trusted quality, supply guarantee, and experience, combined with additional advantages such as IP protection and a well-established partner network.



Click here to learn more:
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A process streamlined through efficiency, expertise, and experience

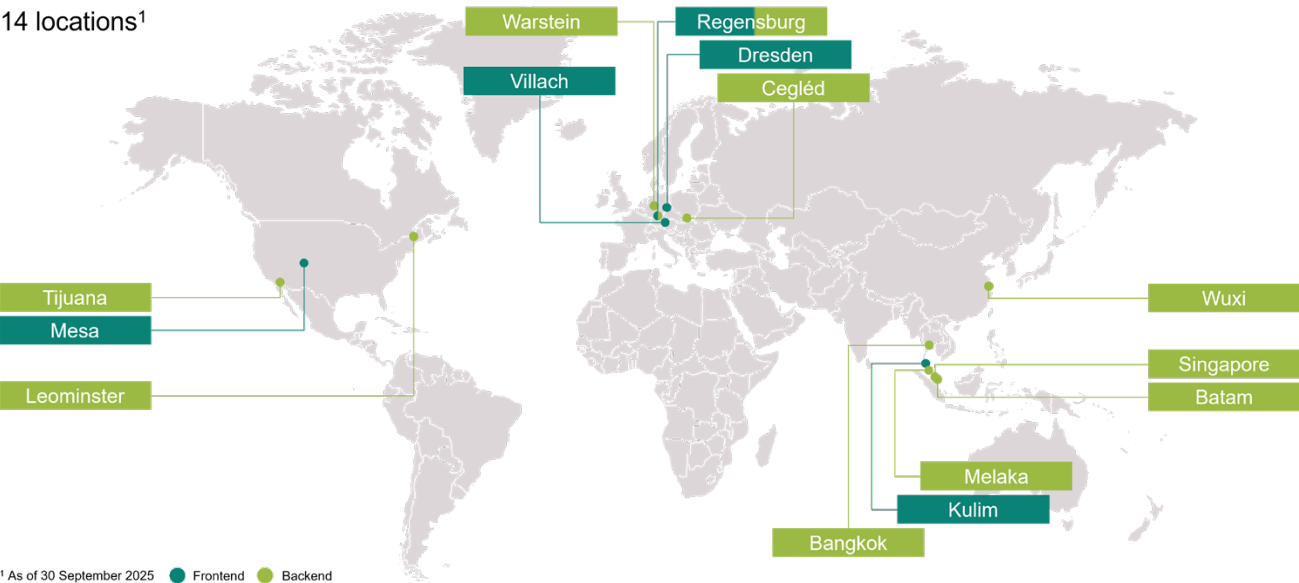
The journey starts with you and a focus on feasibility – we match your needs early on with our 40 years of expertise in building world-class, industry-leading semiconductors and ensure the successful implementation of your requirements.

From technology advantage to supply stability

Whether it is digital, analog, or mixed-signal devices, an embedded processor, or integrated sensors, we have the experience and product know-how. Being one of the largest semiconductor companies, we also have a vast array of IPs. We can integrate almost anything into your chip from our wide variety of sensors, discrete devices, drivers, and many more, including support for higher voltage levels. Our in-house fabrication facilities and design centers around the globe are known for the highest quality standards. We also have well-established partnerships with all major silicon foundries and assembly test fabs to complement our in-house technologies. At every step along the way, we take pride in the highest quality Infineon is known for.

If you are interested and would like to find out further information, visit www.infineon.com/asic

14 locations¹



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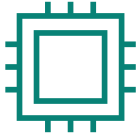
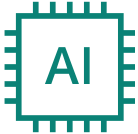
The Infineon Partner Program



Together we create and innovate for our customers' success

Find solutions from our partners to accelerate your next business opportunity. Infineon's global network of partners is an expert in designing products, solutions, and services leveraging Infineon components in 5 key domains: software, hardware, services, tools, and end applications.

The Infineon Partner Program is a global ecosystem of qualified companies, offering knowledge and experience to enable and implement Infineon products. Our associated, preferred, and premium partners help design your device and application based on our components. They have been carefully selected by us on the basis of their competence and ability to design and deliver strong and trustworthy solutions, especially for new technologies and use cases.

				
Hardware	Software	Tools	Services	End applications
Partners manufacturing electronic components, demo boards, and turnkey modules	Partners programming various types of software, algorithms, and operating systems	Partners designing computer programs for the development of embedded systems	Partners providing cloud and engineering services, application support or trainings	Partners creating end products and related applications
... jointly we create and commercialize value-added solutions, while reaching new buyers	... jointly we enhance our portfolio with complementary components and expand technology know-how	... jointly we enable a complete and immersive development experience for customers	... jointly we build up engineering capabilities and offer them to a world class customer network	... jointly we provide customers with state-of-the-art solutions and innovative use cases

Find out more about the Infineon Partner Program, the latest news and solutions from our partners, and much more on our [Partner ecosystems webpage](#).

Looking for a specific partner solution in your region? Our [partner finder](#) provides an overview of our partners and their offerings. Simply specify your search in the dropdown menu and browse through the companies and their solutions to navigate directly to the respective website for further information.

Additionally, use the "Partner solutions" tab on our product and application pages to find out more about Infineon's partner solutions.

 [Click here to learn more:](#)
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